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(71) Applicants *(for all designated States except US)*: **LAM RESEARCH AG** [AT/AT]; SEZ-Strasse 1, A-9500 Villach (AT). **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, California CA-94538 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **FRANK, Dieter** [AT/AT]; Dr. Karl Rennerweg 8, A-9220 Lind ob Velden (AT). **PUGGL, Michael** [AT/AT]; Eitweg 95, A-9421 Eitweg (AT).

(74) Agent: **KONTRUS, Gerhard**; c/o Lam Research AG, SEZ-Strasse 1, A-9500 Villach (AT).

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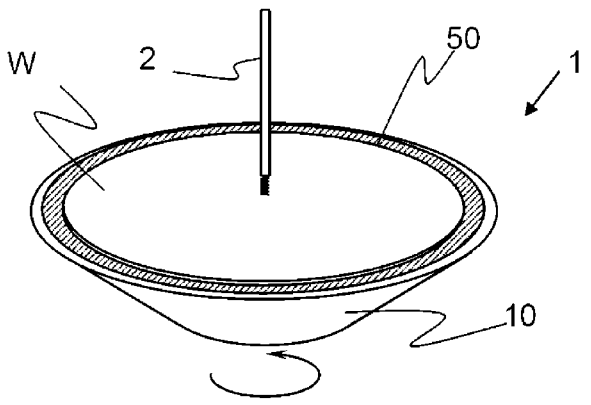
— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

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(54) **Title**: DEVICE AND PROCESS FOR LIQUID TREATMENT OF A WAFER SHAPED ARTICLE

Fig. 1



(57) **Abstract**: A spin chuck in an apparatus for single wafer wet processing has structures at its periphery that, in combination with a supported wafer, form a series of annular nozzles that direct flowing gas from a chuck-facing surface of the wafer, around the edge of the wafer, and exhaust the gas away from the non-chuck- facing surface of the wafer, thereby preventing treatment fluid applied to the non-chuck- facing surface from contacting the edge region of the wafer. Retaining pins with enlarged heads engage the wafer edge and prevent it from being displaced upwardly when a high flow rate of gas is utilized.

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